

The diagram illustrates a semiconductor device 100, which is a rectangular block divided into several functional regions. On the left side, there is a 'switchboard' region containing a circular component labeled 'HT' (103) and a circular component labeled 'R1' (31). A dashed circle labeled '30' is also present in this region. A vertical arrow labeled 'V' points upwards from the bottom of the switchboard region. To the right of the switchboard region is a 'Polisher' region, which contains two circular components labeled 'DR' (8) and '81' (7). A vertical arrow labeled 'V' points upwards from the bottom of the polisher region. The central region of the device 100 contains a large circular component labeled 'R2' (22) and a large circular component labeled 'R3' (11b). A vertical arrow labeled 'VI' points upwards from the bottom of the central region. The top of the device 100 is divided into two main sections: a left section containing a circular component labeled '2CL' (15a) and a circular component labeled 'T/O' (12), and a right section containing a circular component labeled '2CL' (15b) and a circular component labeled 'T/O' (13). The bottom of the device 100 is divided into two main sections: a left section containing a circular component labeled '1CL' (14a) and a circular component labeled 'T/O' (13), and a right section containing a circular component labeled '1CL' (14b) and a circular component labeled 'T/O' (13). The device 100 is connected to a power supply 'V' (102) and a ground 'GND' (101). The device 100 is also connected to a 'switchboard' (103) and a 'Polisher' (101). The device 100 is also connected to a 'switchboard' (103) and a 'Polisher' (101).

FIG. 2

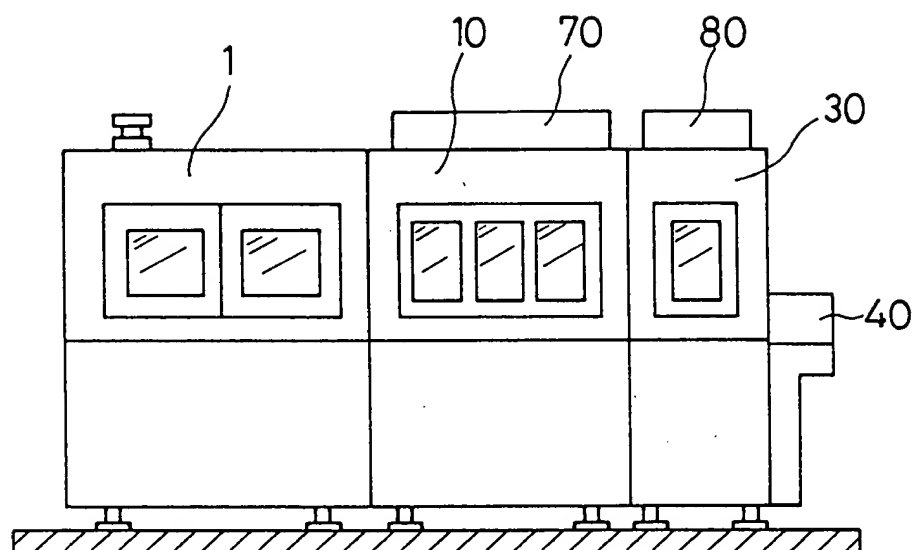
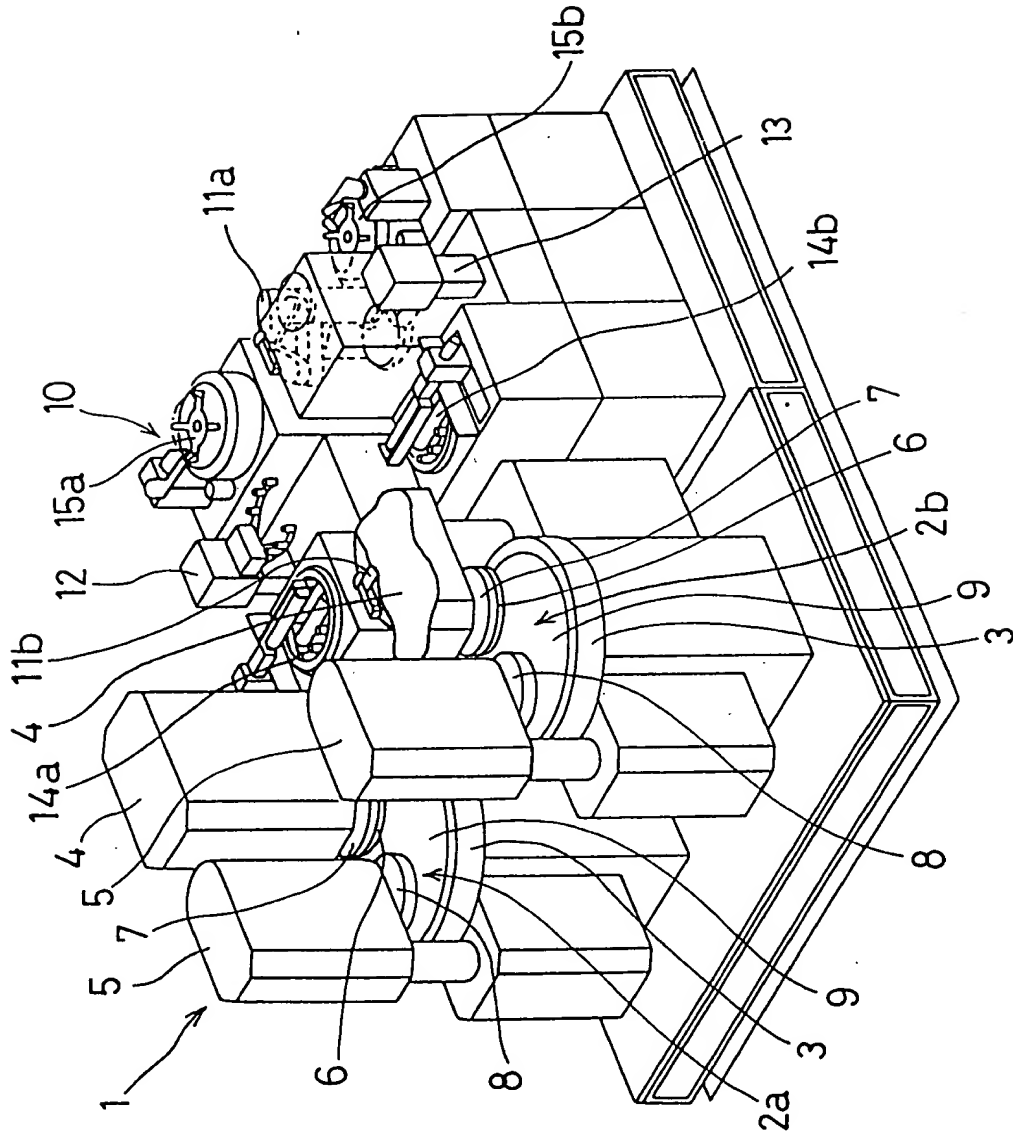


FIG. 2

FIG. 3



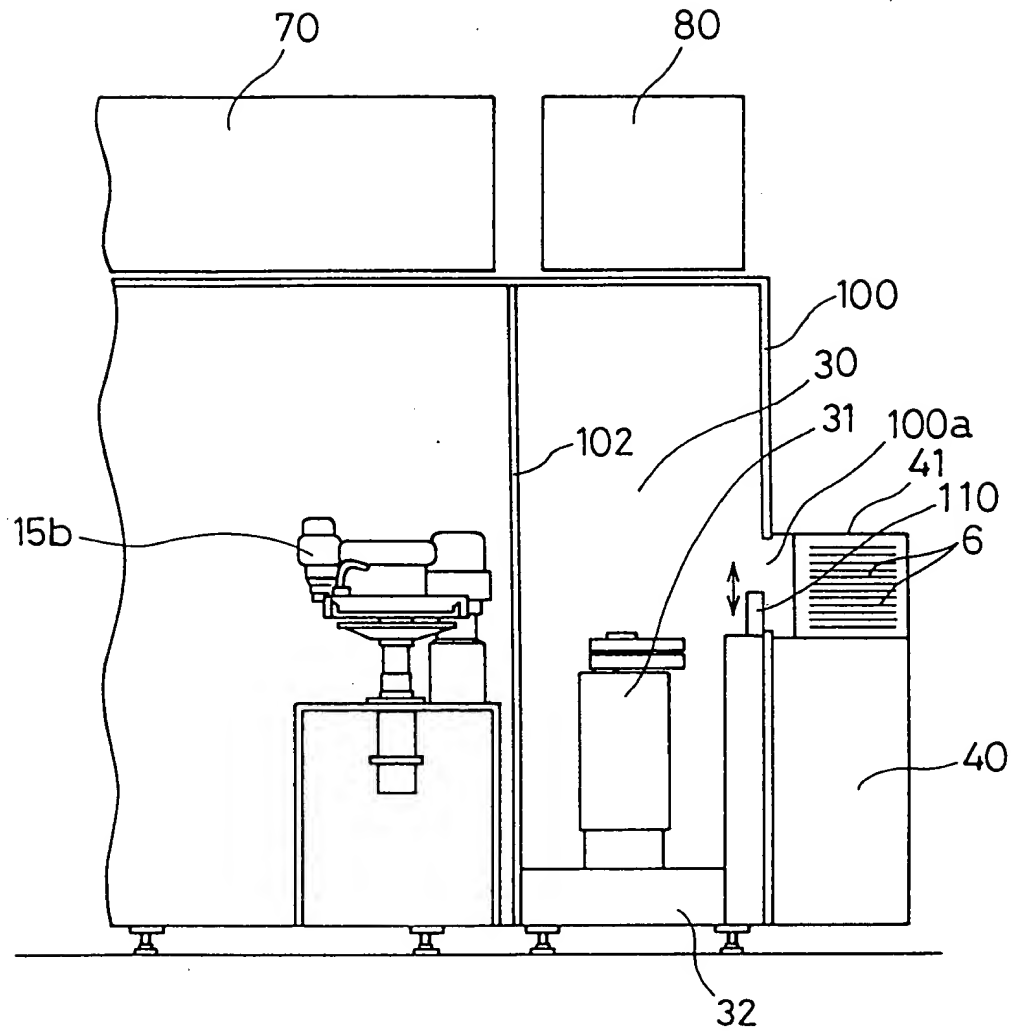
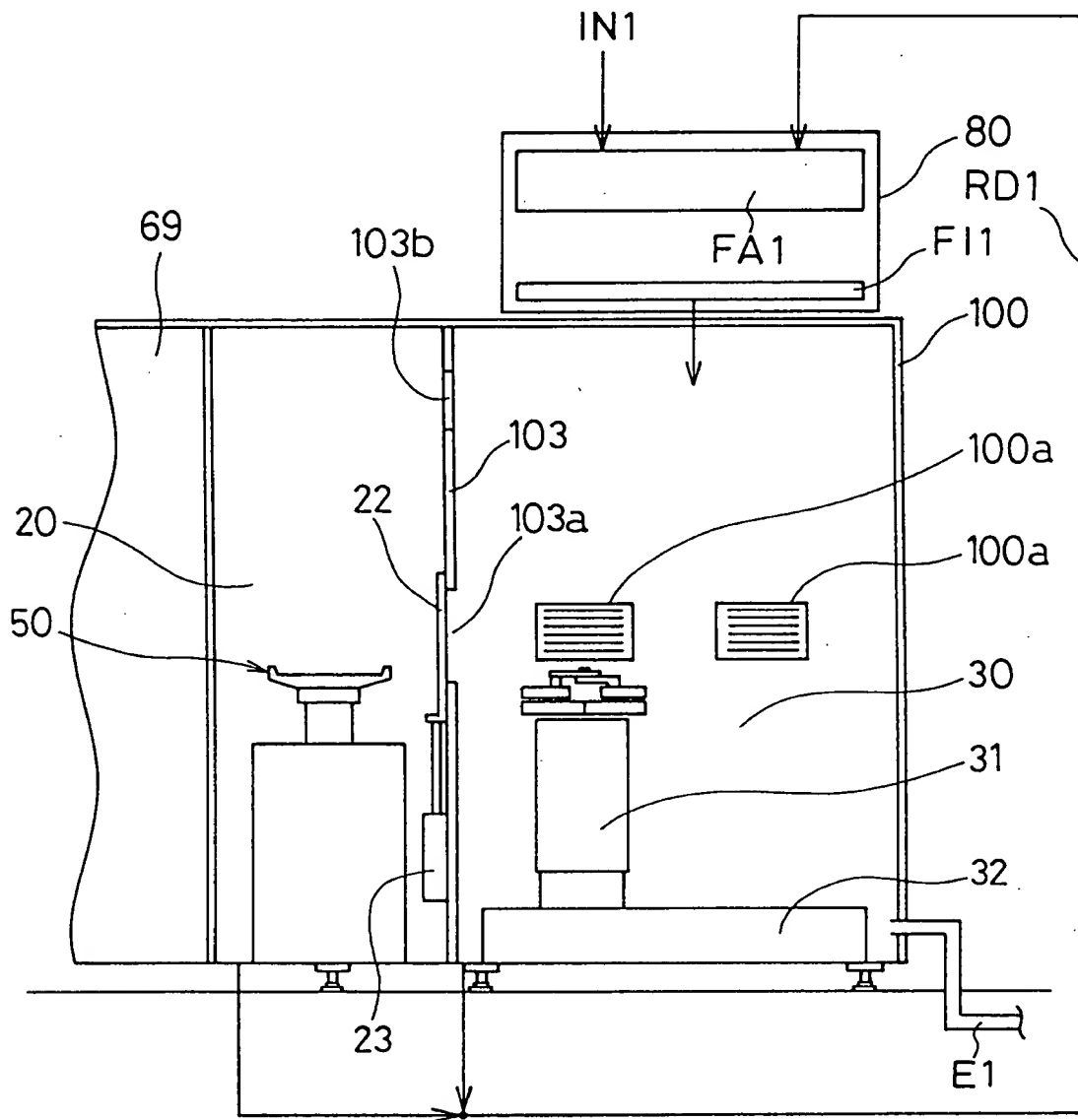
[illegible]

FIG. 5



*F / G. 6*

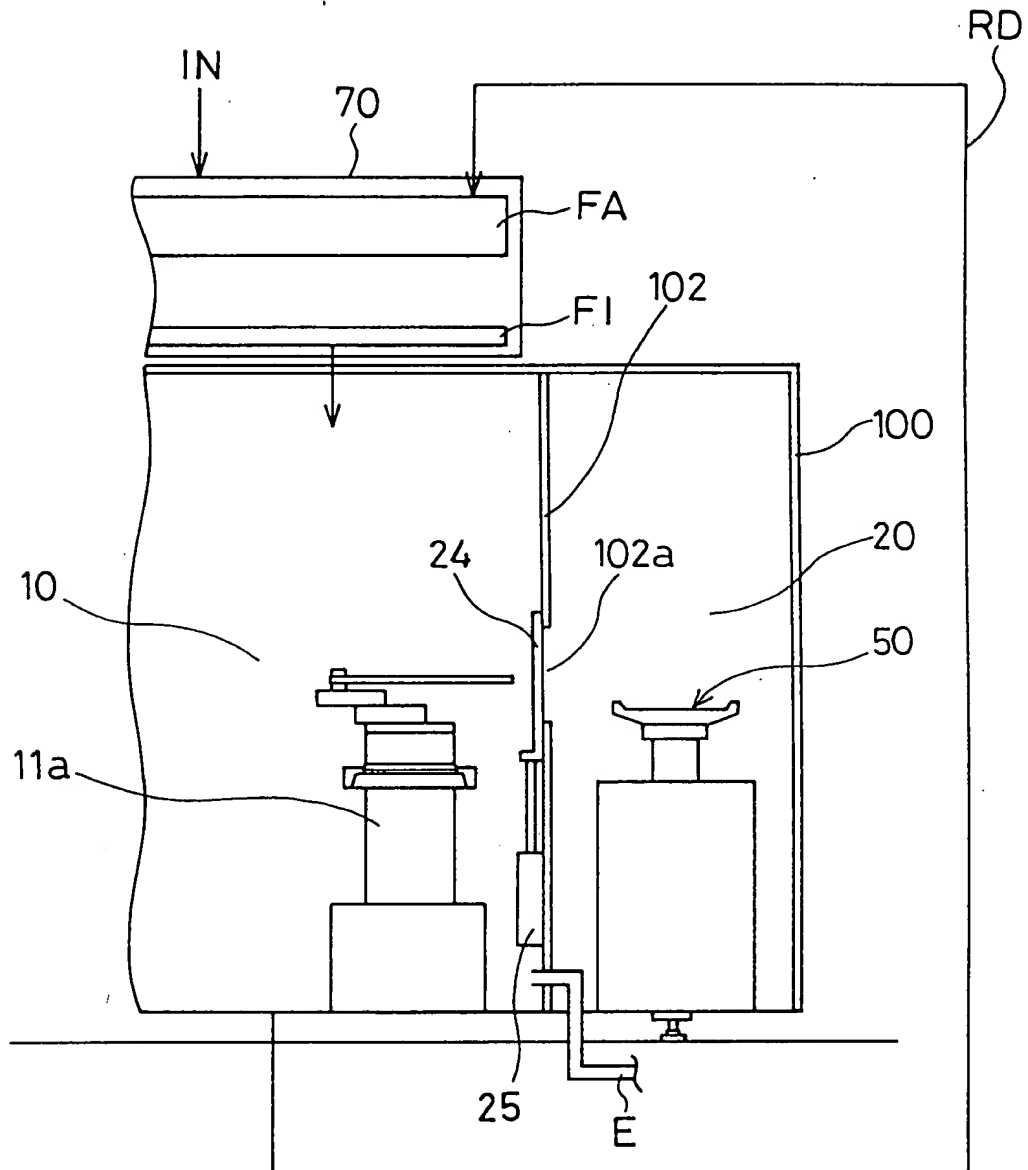
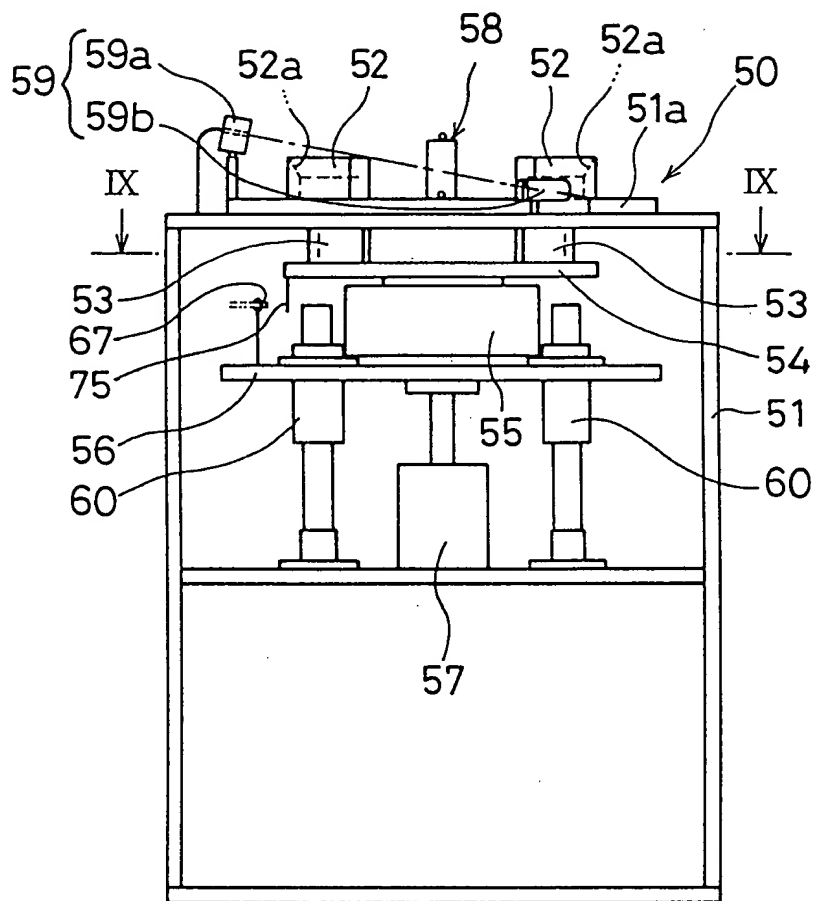


FIG. 7



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FIG. 8

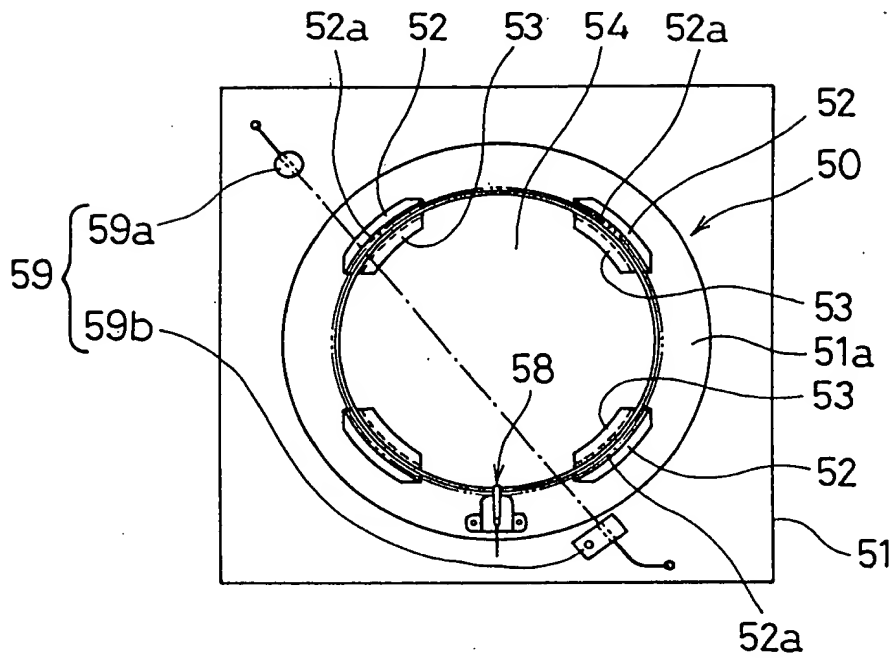


FIG. 9

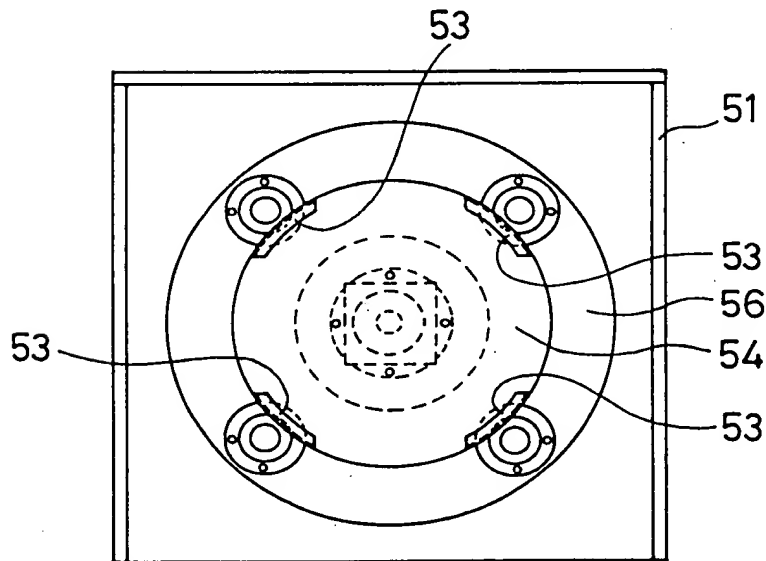


FIG. 8



FIG. 10A

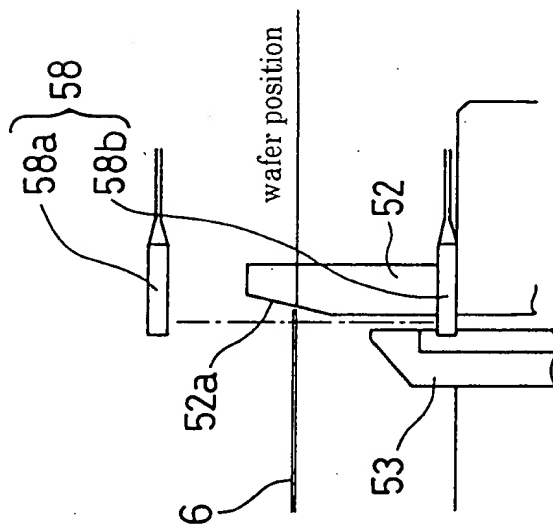


FIG. 10B

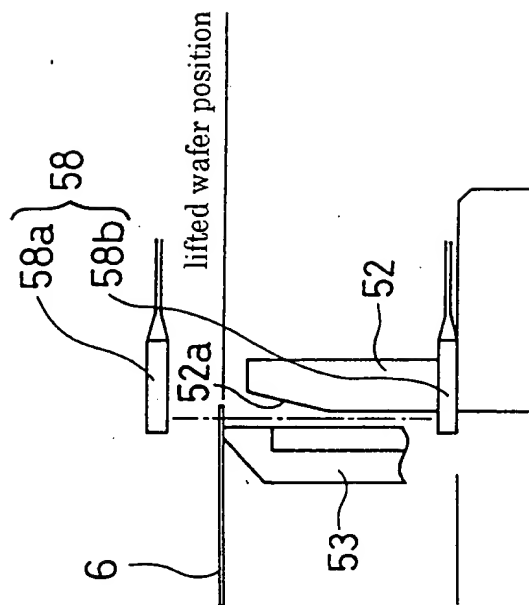


FIG. 11

